

Customer Information Notification

2021040421 : Standardization Packing Method for (H)LQFP in Reels

Note: This notice is NXP Company Proprietary.

Issue Date: Apr 23, 2021 Effective date: Jun 01, 2021

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Management summary

Standardization of the packing method for reels with package types TQFP64 and (H)LQFP144.

The current packing method for products listed is one PQ box in an outer box with cushions.

The new packing method will be single PQ box with foam buffer integrated at the individual Pack Unit level.

Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[X]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
[]Firmware]Other			0

PCN Overview Description

NXP will standardize the packing method for reels with package types TQFP64 and (H)LQFP144.

The current packing method for products listed is one PQ box in an outer box with cushions. The new packing method will be single PQ box with foam buffer.

The single PQ box with foam buffer pass the 1 meter drop-test for the package variants. See details in attached presentation.

The new packing method will be introduced in June 2021. Existing inventory will be shipped until depleted. Reason

To inform the customer about the new packing method for reels for the products in TQFP64 and (H)LQFP144. The new packing method for reels will have less waste of packing material (environmental), reduced shipment volume and more efficient handling times at customer site.

Note with respect to date of planned implementation. The date of implementation is based on consumption/availability of material used in the current pack processing. Excessive consumption of the current material may require an earlier implementation.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality **Data Sheet Revision** No impact to existing datasheet **Disposition of Old Products** Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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Affected OPN	12NC
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PCA8537AH/Q900/1,5	935297895518
PCF8537AH/1,518	935297897518
PCF8537BH/1,518	935297898518
PCA8547AHT/AY	935303763518
PCA8547BHT/AY	935303764518